Nch 600V 35A Power MOSFET

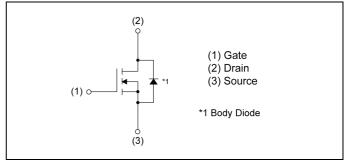
| V_{DSS} | 600V |
|----------------------------|--------|
| R _{DS(on)} (Max.) | 0.102Ω |
| I _D | ±35A |
| P _D | 379W |

Outline TO-247

Features

- 1) Low on-resistance.
- 2) Ultra fast switching speed.
- 3) Parallel use is easy.
- 4) Pb-free lead plating; RoHS compliant

•Inner circuit



Packaging specifications

| | ing opcomodions | |
|--------|---------------------------|-----------|
| | Packing | Tube |
| | Reel size (mm) | - |
| Turn o | Tape width (mm) | - |
| Type | Basic ordering unit (pcs) | 450 |
| | Taping code | C9 |
| | Marking | R6035KNZ1 |

Application

Switching

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

| Parameter | | Symbol | Value | Unit |
|---|--------------------|--------------------|-------------|------|
| Drain - Source voltage | | $V_{\rm DSS}$ | 600 | V |
| Continuous drain current (T _c = 25 | 5°C) | I _D *1 | ±35 | А |
| Pulsed drain current | l _{DP} *2 | ±105 | Α | |
| Cata Carrea valtara | static | V _{GSS} | ±20 | V |
| Gate - Source voltage | AC(f>1Hz) | | ±30 | V |
| Avalanche current, single pulse | · | I _{AS} | 6.6 | Α |
| Avalanche energy, single pulse | | E _{AS} *3 | 796 | mJ |
| Power dissipation (T _c = 25°C) | | P_{D} | 379 | W |
| Junction temperature | | T _j | 150 | °C |
| Operating junction and storage te | emperature range | T _{stg} | -55 to +150 | °C |

●Thermal resistance

| Downwortow | Cymah al | Values | | | l lesit |
|--|----------------------|--------|------|------|---------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | R _{thJC} *4 | - | - | 0.33 | °C/W |
| Thermal resistance, junction - ambient | R _{thJA} | - | - | 30 | °C/W |
| Soldering temperature, wavesoldering for 10s | T _{sold} | - | - | 265 | °C |

• Electrical characteristics $(T_a = 25^{\circ}C)$

| Parameter | Symbol Conditions | | Values | | | Unit | |
|---|------------------------|---|--------|-------|-------|-------|--|
| - Farameter | Symbol | Conditions | Min. | Тур. | Max. | Offic | |
| Drain - Source breakdown voltage | V _{(BR)DSS} | $V_{GS} = 0V$, $I_D = 1mA$ | 600 | - | - | V | |
| | | V _{DS} = 600V, V _{GS} = 0V | | | | | |
| Zero gate voltage drain current | I _{DSS} | $T_j = 25^{\circ}C$ | - | - | 100 | μΑ | |
| didiri odriorit | | $T_j = 125^{\circ}C$ | - | - | 1000 | | |
| Gate - Source leakage current | I _{GSS} | V _{GS} = ±20V, V _{DS} = 0V | - | - | ±100 | nA | |
| Gate threshold voltage | $V_{GS(th)}$ | V _{DS} = 10V, I _D = 1mA | 3 | - | 5 | V | |
| | | V _{GS} = 10V, I _D = 18.1A | | | | | |
| Static drain - source on - state resistance | R _{DS(on)} *5 | $T_j = 25^{\circ}C$ | - | 0.092 | 0.102 | Ω | |
| | | $T_j = 125^{\circ}C$ | - | 0.200 | - | | |
| Gate resistance | R_{G} | f = 1MHz, open drain | - | 1.0 | - | Ω | |

● Electrical characteristics (T_a = 25°C)

| Darramatar | Cymah al | Conditions | | Values | | | |
|--------------------------------|---|---------------------------------------|------|--------|------|------|--|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit | |
| Forward Transfer Admittance | $ Y_{fs} ^{*5}$ $V_{DS} = 10V, I_D = 17.5A$ | | 11 | 22 | - | S | |
| Input capacitance | C _{iss} | V _{GS} = 0V | - | 3000 | - | | |
| Output capacitance | C _{oss} | V _{DS} = 25V | - | 2300 | - | pF | |
| Reverse transfer capacitance | C _{rss} | f = 1MHz | - | 80 | - | | |
| Turn - on delay time | t _{d(on)} *5 | $V_{DD} \simeq 300V$, $V_{GS} = 10V$ | - | 45 | - | | |
| Rise time | t _r *5 | I _D = 17.5A | - | 150 | - | 20 | |
| Turn - off delay time | t _{d(off)} *5 | $R_L \simeq 17.4\Omega$ | - | 90 | 1 | ns | |
| Fall time | t _f *5 | $R_G = 10\Omega$ | - | 95 | - | | |

● Gate charge characteristics (T_a = 25°C)

| Darameter | Cymah al | Conditions | Values | | | Linit | |
|----------------------|------------------------|--|--------|------|------|-------|--|
| Parameter Symbol | | Conditions | Min. | Тур. | Max. | Unit | |
| Total gate charge | Q_g^{*5} | V _{DD} ≈ 300V | - | 72 | - | | |
| Gate - Source charge | Q _{gs} *5 | I _D = 35A | - | 20 | - | nC | |
| Gate - Drain charge | Q _{gd} *5 | V _{GS} = 10V | - | 30 | - | | |
| Gate plateau voltage | V _(plateau) | V _{DD} ≈ 300V, I _D = 35A | - | 6.6 | - | V | |

^{*1} Limited only by maximum channel temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \doteqdot 500 μ H, V_{DD}=50V, R_G=25 Ω , STARTING T $_{j}$ =25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Pulsed

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

| Parameter | Symbol | Canditions | Values | | | Unit |
|-------------------------------|---------------------|---|--------|------|------|------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Continuous forward current | I _S *1 | T - 25°C | - | 1 | 35 | А |
| Pulse forward current | I _{SP} *2 | T _C = 25°C | - | - | 105 | А |
| Forward voltage | V _{SD} *5 | $V_{GS} = 0V, I_{S} = 35A$ | - | - | 1.5 | V |
| Reverse recovery time | t _{rr} *5 | | - | 605 | - | ns |
| Reverse recovery charge | Q _{rr} *5 | I _S = 35A di/dt = 100A/µs | - | 14.5 | - | μC |
| Peak reverse recovery current | I _{rrm} *5 | 3 1007 V µ0 | - | 45 | - | Α |

Typical transient thermal characteristics

| Symbol | Value | Unit |
|------------------|-------|------|
| R _{th1} | 0.151 | |
| R _{th2} | 0.428 | K/W |
| R _{th3} | 0.250 | |

| Symbol | Value | Unit |
|------------------|-------|------|
| C _{th1} | 0.018 | |
| C _{th2} | 0.400 | Ws/K |
| C _{th3} | 15.4 | |

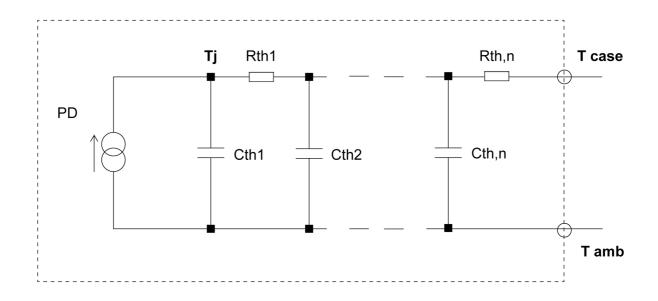


Fig.1 Power Dissipation Derating Curve

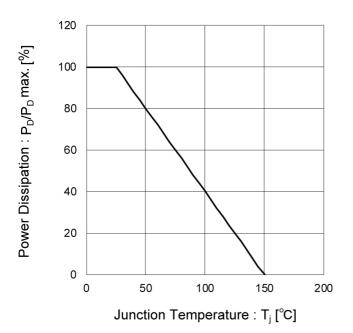


Fig.2 Maximum Safe Operating Area

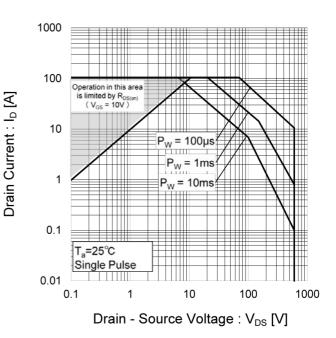


Fig.3 Avalanche Energy Derating
Curve vs. Junction Temperature

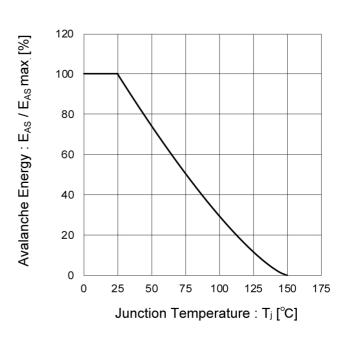


Fig.4 Typical Output Characteristics(I)

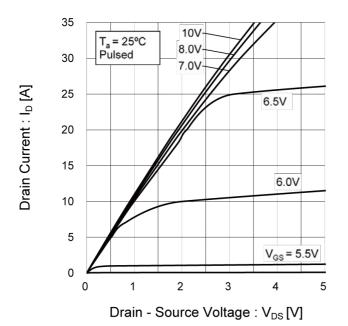
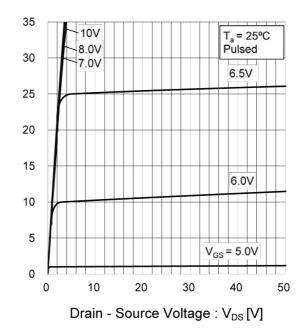


Fig.5 Typical Output Characteristics(II)



Drain Current : I_D [A]



Fig.6 Breakdown Voltage vs.

Junction Temperature

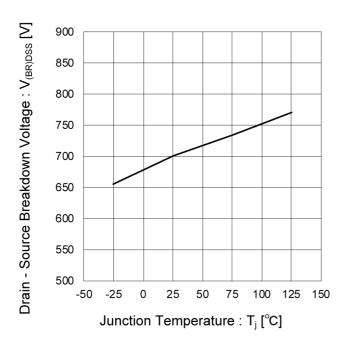


Fig.7 Typical Transfer Characteristics

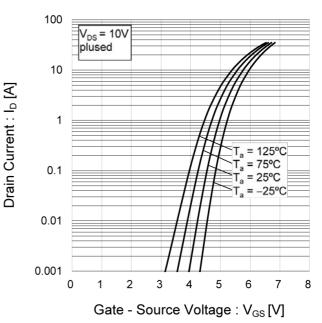


Fig.8 Gate Threshold Voltage vs.
Junction Temperature

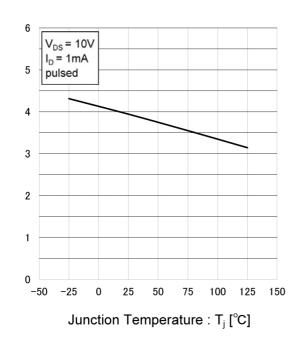
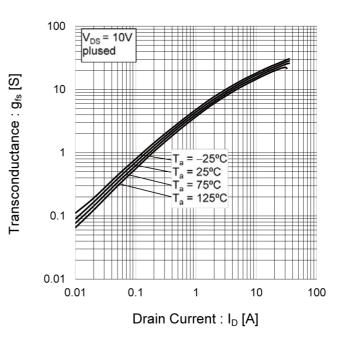


Fig.9 Forward Transfer Admittance vs.

Drain Current



Gate Threshold Voltage : $V_{GS(th)}\left[V\right]$

Fig.10 Static Drain - Source On - State
Resistance vs. Gate Source Voltage

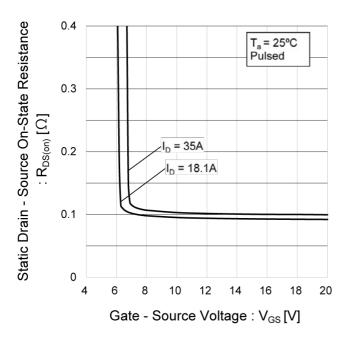


Fig.11 Static Drain - Source On - State Resistance vs. Junction Temperature

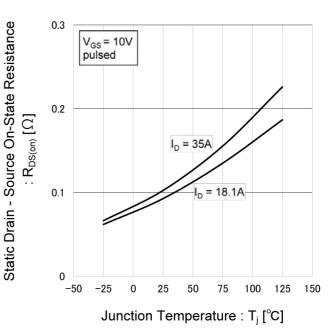


Fig.12 Static Drain - Source On - State Resistance vs. Drain Current(I)

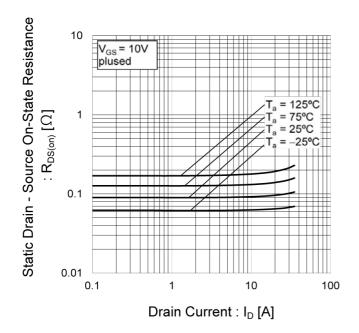
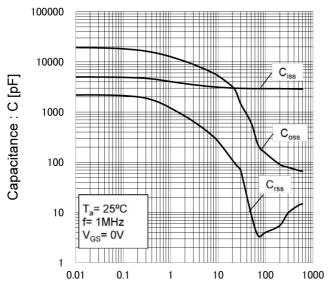


Fig.13 Typical Capacitance vs. Drain - Source Voltage



Drain - Source Voltage : V_{DS} [V]

Fig.14 Switching Characteristics

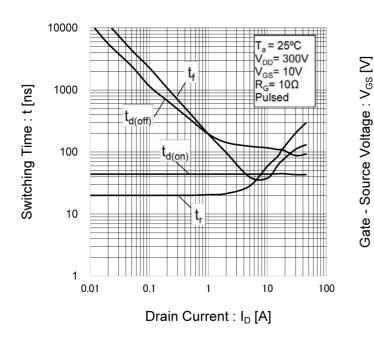


Fig.15 Dynamic Input Characteristics

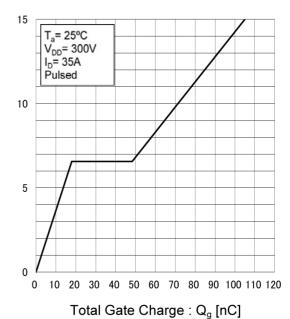


Fig.16 Inverse Diode Forward Current vs. Source - Drain Voltage

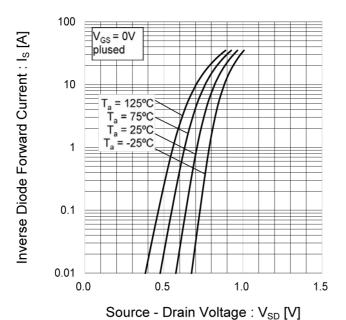
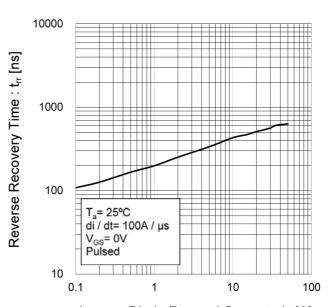


Fig.17 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current : I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

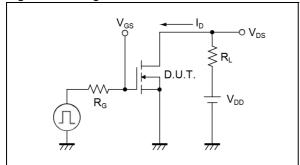


Fig.2-1 Gate Charge Measurement Circuit

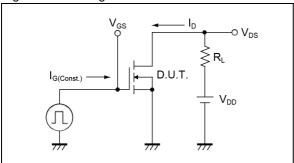


Fig.3-1 Avalanche Measurement Circuit

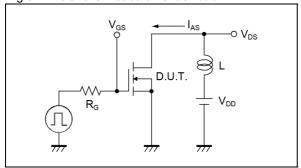


Fig.4-1 dv/dt Measurement Circuit

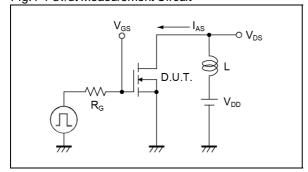


Fig.5-1 dv/dt Measurement Circuit

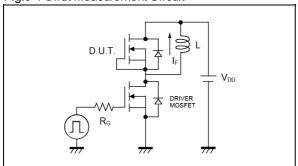


Fig.1-2 Switching Waveforms

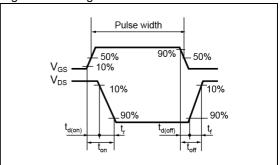


Fig.2-2 Gate Charge Waveform

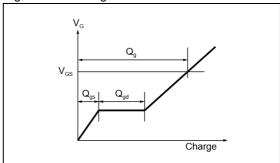


Fig.3-2 Avalanche Waveform

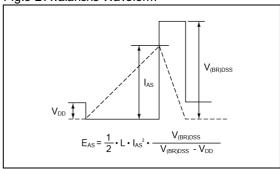


Fig.4-2 dv/dt Waveform

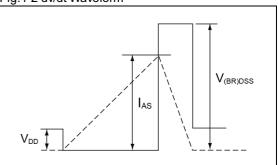
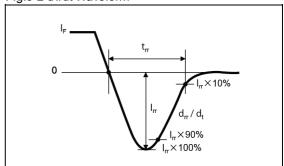
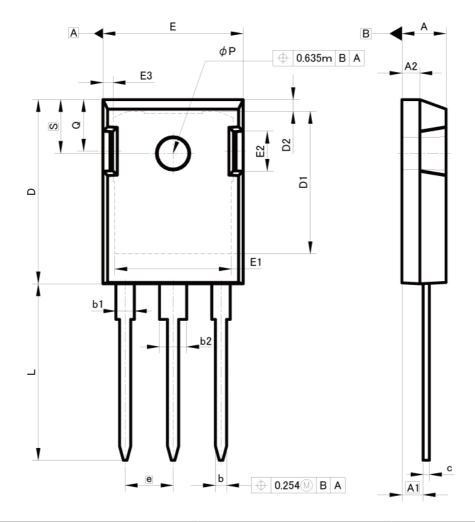


Fig.5-2 dv/dt Waveform



Dimensions

TO-247



| DIM | MILIM | ETERS | INC | HES |
|-----|-------|-------|-------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 4.83 | 5.21 | 0.19 | 0.205 |
| A1 | 2.29 | 2.54 | 0.09 | 0.1 |
| A2 | 1.91 | 2.16 | 0.075 | 0.085 |
| b | 1.14 | 1.40 | 0.045 | 0.055 |
| b1 | 1.91 | 2.20 | 0.075 | 0.087 |
| b2 | 2.92 | 3.20 | 0.115 | 0.126 |
| С | 0.61 | 0.80 | 0.024 | 0.031 |
| D | 20.80 | 21.34 | 0.819 | 0.84 |
| D1 | 17.43 | 17.83 | 0.686 | 0.702 |
| E | 15.75 | 16.13 | 0.62 | 0.635 |
| е | 5.4 | 45 | 0.2 | 22 |
| N | | 3 | (| 3 |
| L | 19.81 | 20.57 | 0.78 | 0.81 |
| L1 | 3.81 | 4.07 | 0.15 | 0.16 |
| ФР | 3.55 | 3.65 | 0.14 | 0.144 |
| Q | 5.59 | 6.20 | 0.22 | 0.244 |
| S | 6. | 15 | 0.2 | 24 |

Dimension in mm/inches



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| JAPAN | USA | EU | CHINA |
|---------|----------|----------|----------|
| CLASSⅢ | CLASSⅢ | CLASSIIb | CL ACCTI |
| CLASSIV | CLASSIII | CLASSⅢ | CLASSIII |

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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R6035KNZ1 - Web Page

Distribution Inventory

| Part Number | R6035KNZ1 |
|-----------------------------|-----------|
| Package | TO-247 |
| Unit Quantity | 450 |
| Minimum Package Quantity | 450 |
| Packing Type | Bulk |
| Constitution Materials List | inquiry |
| RoHS | Yes |